## WHAT IS CLAIMED IS:

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 An apparatus for forming a deposited film, comprising:

a chamber capable of maintaining an interior thereof under vacuum;

a source gas supply piping for supplying a source gas into the chamber;

an evacuation system piping for evacuating the interior of the chamber; and

a gas supply piping for use in opening to atmosphere, for supplying a gas for returning a pressure within the chamber to atmospheric pressure,

wherein a plurality of shut-off valves are provided in series between a gas source of the gas for returning the pressure within the chamber to the atmospheric pressure and the chamber, and wherein a pressure gauge and/or an evacuating means are provided between the plurality of shut-off valves.

- 2. The apparatus according to claim 1, wherein the evacuating means is independent of an evacuating means for evacuating the interior of the chamber.
- The apparatus according to claim 1, wherein
   the chamber is provided in plurality.
  - 4. The apparatus according to claim 3, wherein

the gas supply piping for use in opening to atmosphere is diverged toward a plurality of chambers, and a manually-operated valve is provided midway in the diverged piping.

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- 5. The apparatus according to claim 1, further comprising a programmed means for automatically depositing a film.
- 10 6. The apparatus according to claim 5, wherein the pressure gauge is a pressure gauge with an alarm contact.
- 7. A method of forming a deposited film,

  15 comprising supplying a source gas into a chamber to

  form a deposited film on a substrate, and thereafter,

  introducing a gas for opening to atmosphere into the

  chamber to return a pressure within the chamber to

  atmospheric pressure,
- wherein a plurality of shut-off valves are provided in series between a gas source of the gas for returning the pressure within the chamber to the atmospheric pressure and the chamber; and

wherein the plurality of shut-off valves are closed to perform film deposition while a source gas is being supplied into the chamber.

- 8. The method according to claim 7, wherein a pressure between the plurality of shut-off valves is reduced to perform film deposition.
- 9. The method according to claim 7, wherein a space between the plurality of shut-off valves is filled with a non-reactive gas to perform film deposition.